

SN54ABT16646, SN74ABT16646 16-BIT BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

SCBS212D – JUNE 1992 – REVISED JULY 1999

- Members of the Texas Instruments *Widebus™* Family
- State-of-the-Art *EPIC-II B™* BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs ($-32\text{-mA } I_{OH}$, $64\text{-mA } I_{OL}$)
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'ABT16646 devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers.

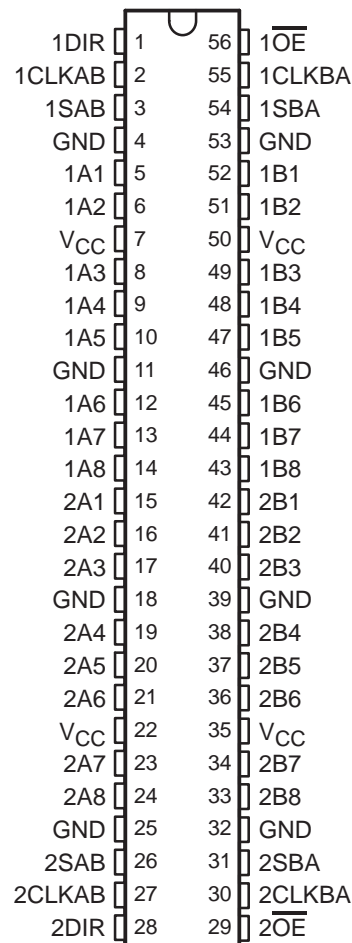
These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'ABT16646 devices.

Output-enable (\overline{OE}) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. The direction control (DIR) determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data can be stored in one register and/or B data can be stored in the other register.

When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54ABT16646 . . . WD PACKAGE
SN74ABT16646 . . . DGG OR DL PACKAGE
(TOP VIEW)



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**TEXAS
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16-BIT BUS TRANSCEIVERS AND REGISTERS

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description (continued)

The SN54ABT16646 is characterized for operation over the full military temperature range of -55°C to 125°C .
The SN74ABT16646 is characterized for operation from -40°C to 85°C .

FUNCTION TABLE

INPUTS						DATA I/O†		OPERATION OR FUNCTION
$\overline{\text{OE}}$	DIR	CLKAB	CLKBA	SAB	SBA	A1–A8	B1–B8	
X	X	↑	X	X	X	Input	Unspecified	Store A, B unspecified†
X	X	X	↑	X	X	Unspecified	Input	Store B, A unspecified†
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B Bus
L	H	H or L	X	H	X	Input	Output	Stored A data to bus

† The data-output functions can be enabled or disabled by various signals at $\overline{\text{OE}}$ or DIR. Data-input functions always are enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

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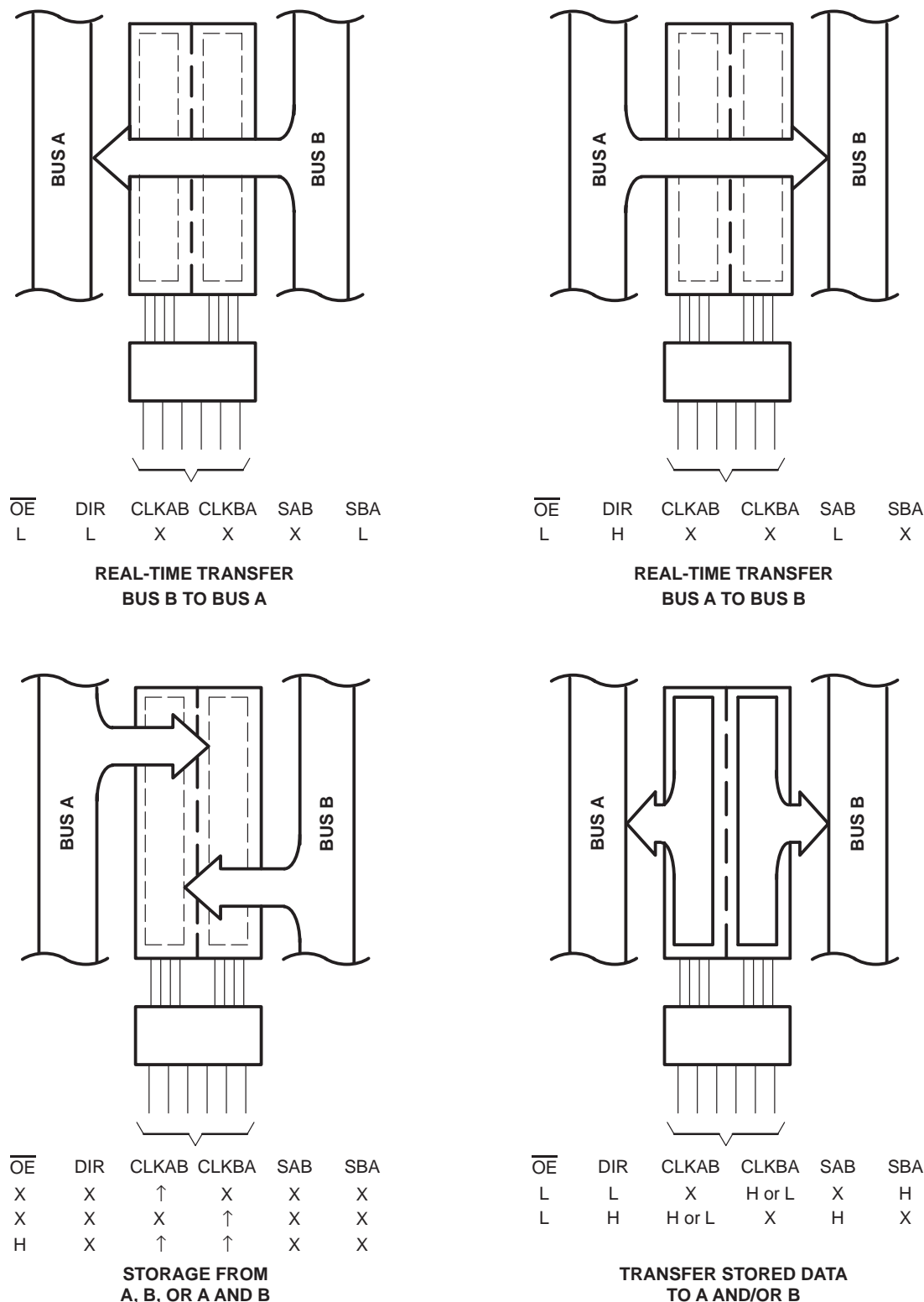


Figure 1. Bus-Management Functions

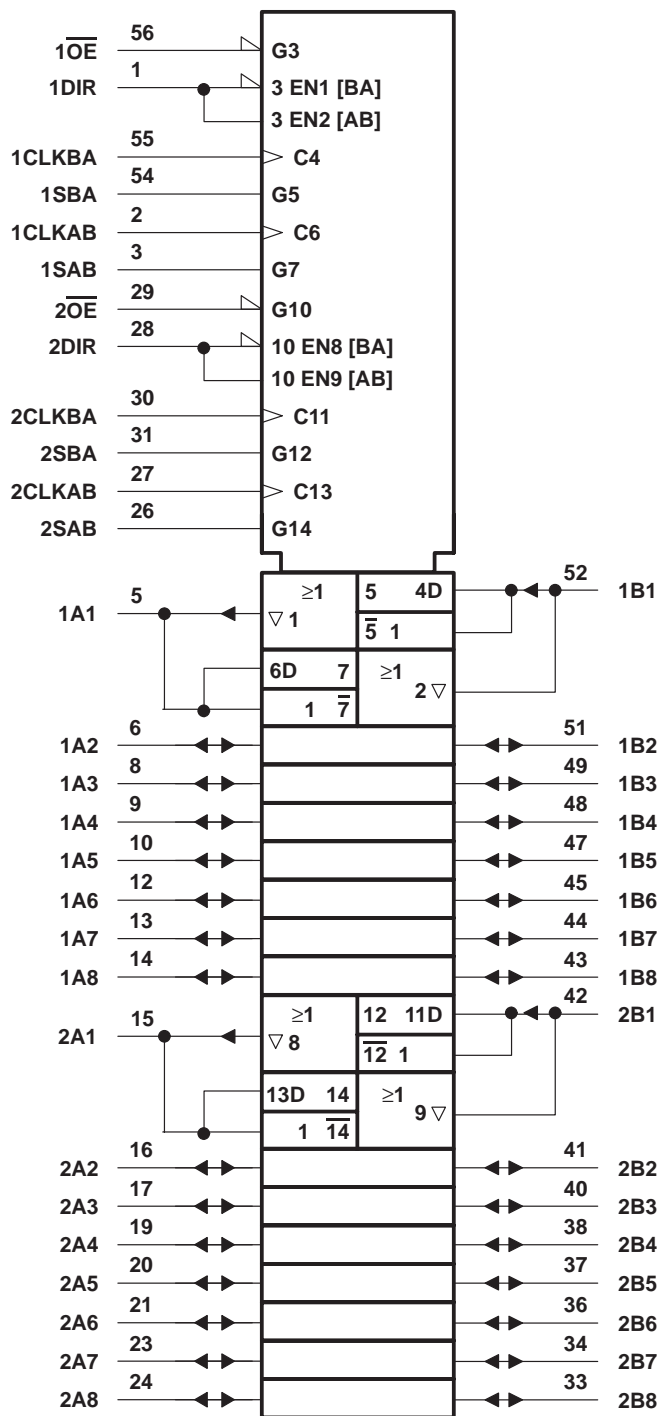
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

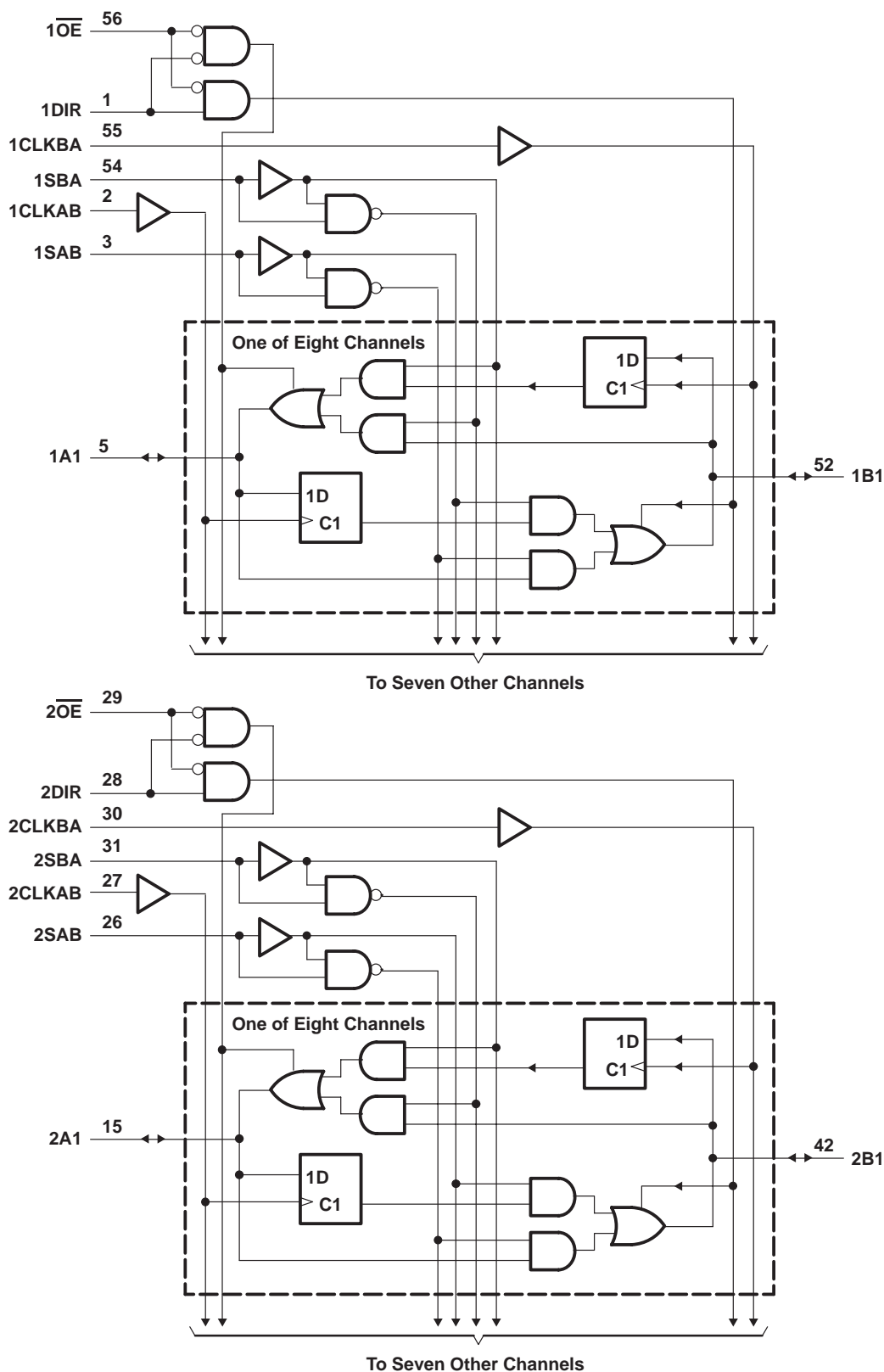
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logic diagram (positive logic)



SN54ABT16646, SN74ABT16646

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O	–0.5 V to 5.5 V
Current into any output in the low state, I_O : SN54ABT16646	96 mA
SN74ABT16646	128 mA
Input clamp current, I_{IK} ($V_I < 0$)	–18 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		SN54ABT16646		SN74ABT16646		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled			10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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16-BIT BUS TRANSCEIVERS AND REGISTERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T _A = 25°C			SN54ABT16646		SN74ABT16646		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V _{IK}		V _{CC} = 4.5 V, I _I = −18 mA		−1.2			−1.2		−1.2		V
V _{OH}		V _{CC} = 4.5 V, I _{OH} = −3 mA		2.5			2.5		2.5		V
		V _{CC} = 5 V, I _{OH} = −3 mA		3			3		3		
		V _{CC} = 4.5 V	I _{OH} = −24 mA	2			2				
			I _{OH} = −32 mA	2*					2		
V _{OL}		V _{CC} = 4.5 V	I _{OL} = 48 mA	0.55			0.55				V
			I _{OL} = 64 mA	0.55*					0.55		
V _{hys}				100							mV
I _I	Control inputs	V _{CC} = 5.5 V, V _I = V _{CC} or GND		±1			±1		±1		μA
	A or B ports			±20			±20		±20		
I _{OZH} ‡		V _{CC} = 5.5 V, V _O = 2.7 V		10			10		10		μA
I _{OZL} ‡		V _{CC} = 5.5 V, V _O = 0.5 V		−10			−10		−10		μA
I _{off}		V _{CC} = 0, V _I or V _O ≤ 4.5 V		±100					±100		μA
I _{CEX}		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high	50			50		50		μA
I _O §		V _{CC} = 5.5 V, V _O = 2.5 V		−50	−100	−180	−50	−180	−50	−180	mA
I _{CC}	A or B ports	V _{CC} = 5.5 V, I _O = 0, V _I = V _{CC} or GND	Outputs high	2			2		2		mA
			Outputs low	32			32		32		
			Outputs disabled	2			2		2		
ΔI _{CC} ¶	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	Outputs enabled	50			50		50		μA
			Outputs disabled	50			50		50		
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND	50			50		50			
C _i	Control inputs	V _I = 2.5 V or 0.5 V		4							pF
C _{io}	A or B ports	V _O = 2.5 V or 0.5 V		8							pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V_{CC} = 5 V.

‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN54ABT16646		UNIT		
		V _{CC} = 5 V, T _A = 25°C			MIN	MAX
		MIN	MAX			
f _{clock}	Clock frequency	125		125	MHz	
t _w	Pulse duration, CLK high or low	4.3		4.3	ns	
t _{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3.5		4	ns	
t _h	Hold time, A or B after CLKAB↑ or CLKBA↑	0.5		0.5	ns	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		SN74ABT16646		UNIT		
		$V_{CC} = 5\text{ V},$ $T_A = 25^{\circ}\text{C}$			MIN	MAX
		MIN	MAX			
f_{clock}	Clock frequency	125		125	MHz	
t_W	Pulse duration, CLK high or low	4.3		4.3	ns	
t_{su}	Setup time, A or B before CLKAB↑ or CLKBA↑	3		3	ns	
t_h	Hold time, A or B after CLKAB↑ or CLKBA↑	0		0	ns	

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT16646					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f _{max}			125			125		MHz
t _{PLH}	CLKBA or CLKAB	A or B	1.5	3.1	4	1	5	ns
t _{PHL}			1.5	3.2	4.1	1	5	
t _{PLH}	A or B	B or A	1	2.3	3.2	0.6	4	ns
t _{PHL}			1	3	4.1	0.6	4.9	
t _{PLH}	SAB or SBA†	B or A	1	2.9	4.3	0.6	5.3	ns
t _{PHL}			1	3.1	4.3	0.6	5.3	
t _{PZH}	\overline{OE}	A or B	1	3.4	4.6	0.6	5.9	ns
t _{PZL}			1.5	3.5	5.3	1	6	
t _{PHZ}	\overline{OE}	A or B	1.5	3.9	5.6	1	6.4	ns
t _{PLZ}			1.5	3.1	4.4	1	4.7	
t _{PZH}	DIR	A or B	1	3.2	4.5	0.6	5.8	ns
t _{PZL}			1.5	3.4	5.1	1	6.7	
t _{PHZ}	DIR	A or B	2	4.2	5.9	1.2	7.1	ns
t _{PLZ}			1.5	3.6	5.1	1	6.2	

† These parameters are measured with the internal output state of the storage register opposite that of the bus input.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50$ pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT16646					UNIT
			V _{CC} = 5 V, T _A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
f _{max}			125			125		MHz
t _{PLH}	CLKBA or CLKAB	A or B	1.5	3.1	4	1.5	4.9	ns
t _{PHL}			1.5	3.2	4.1	1.5	4.7	
t _{PLH}	A or B	B or A	1	2.3	3.2	1	3.9	ns
t _{PHL}			1	3	4.1	1	4.6	
t _{PLH}	SAB or SBA†	B or A	1	2.9	4.3	1	5	ns
t _{PHL}			1	3.1	4.3	1	5	
t _{PZH}	\overline{OE}	A or B	1	3.4	4.6	1	5.5	ns
t _{PZL}			1.5	3.5	4.9	1.5	5.7	
t _{PHZ}	\overline{OE}	A or B	1.5	3.9	4.9	1.5	5.4	ns
t _{PLZ}			1.5	3.1	4.1	1.5	4.5	
t _{PZH}	DIR	A or B	1	3.2	4.5	1	5.4	ns
t _{PZL}			1.5	3.4	4.8	1.5	5.6	
t _{PHZ}	DIR	A or B	2	4.2	5.7	2	6.7	ns
t _{PLZ}			1.5	3.6	5.1	1.5	5.9	

† These parameters are measured with the internal output state of the storage register opposite that of the bus input.



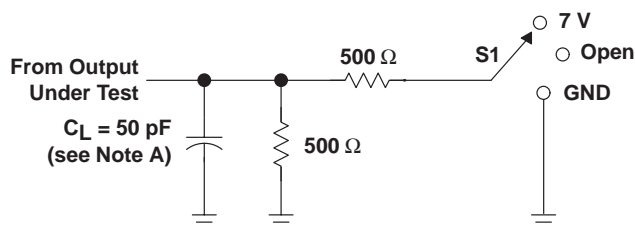
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16-BIT BUS TRANSCEIVERS AND REGISTERS

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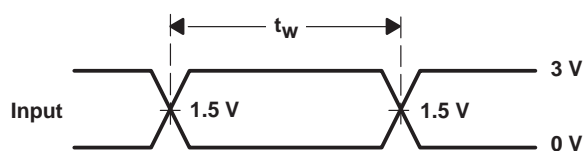
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PARAMETER MEASUREMENT INFORMATION

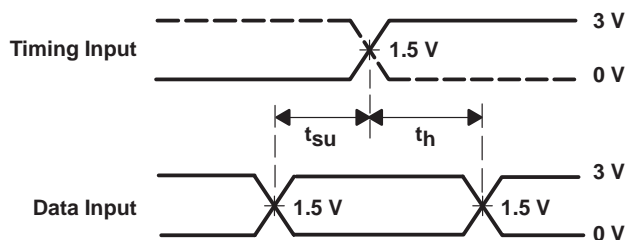


LOAD CIRCUIT

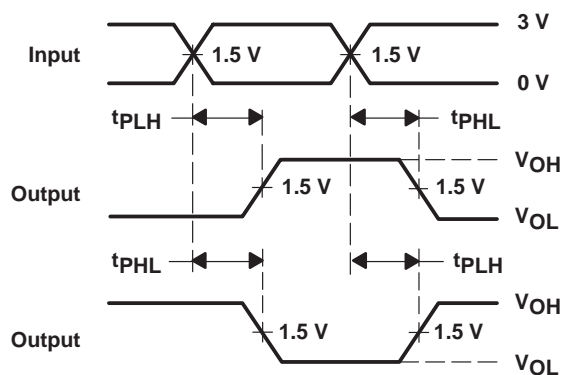
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



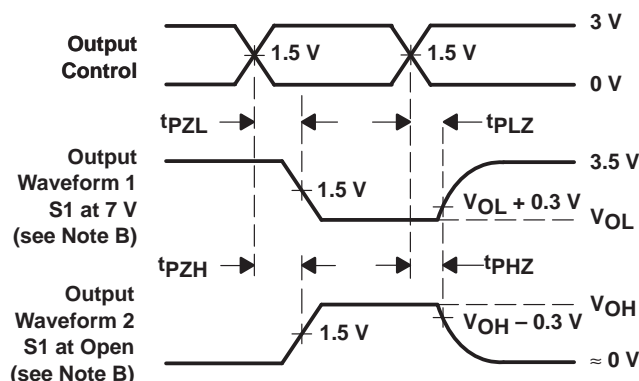
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74ABT16646DGGR	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16646
SN74ABT16646DGGR.B	Active	Production	TSSOP (DGG) 56	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16646
SN74ABT16646DL	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16646
SN74ABT16646DL.B	Active	Production	SSOP (DL) 56	20 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16646
SN74ABT16646DLR	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16646
SN74ABT16646DLR.B	Active	Production	SSOP (DL) 56	1000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT16646

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16646DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.9	14.7	1.4	12.0	24.0	Q1
SN74ABT16646DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16646DGGR	TSSOP	DGG	56	2000	356.0	356.0	45.0
SN74ABT16646DLR	SSOP	DL	56	1000	356.0	356.0	53.0

TUBE

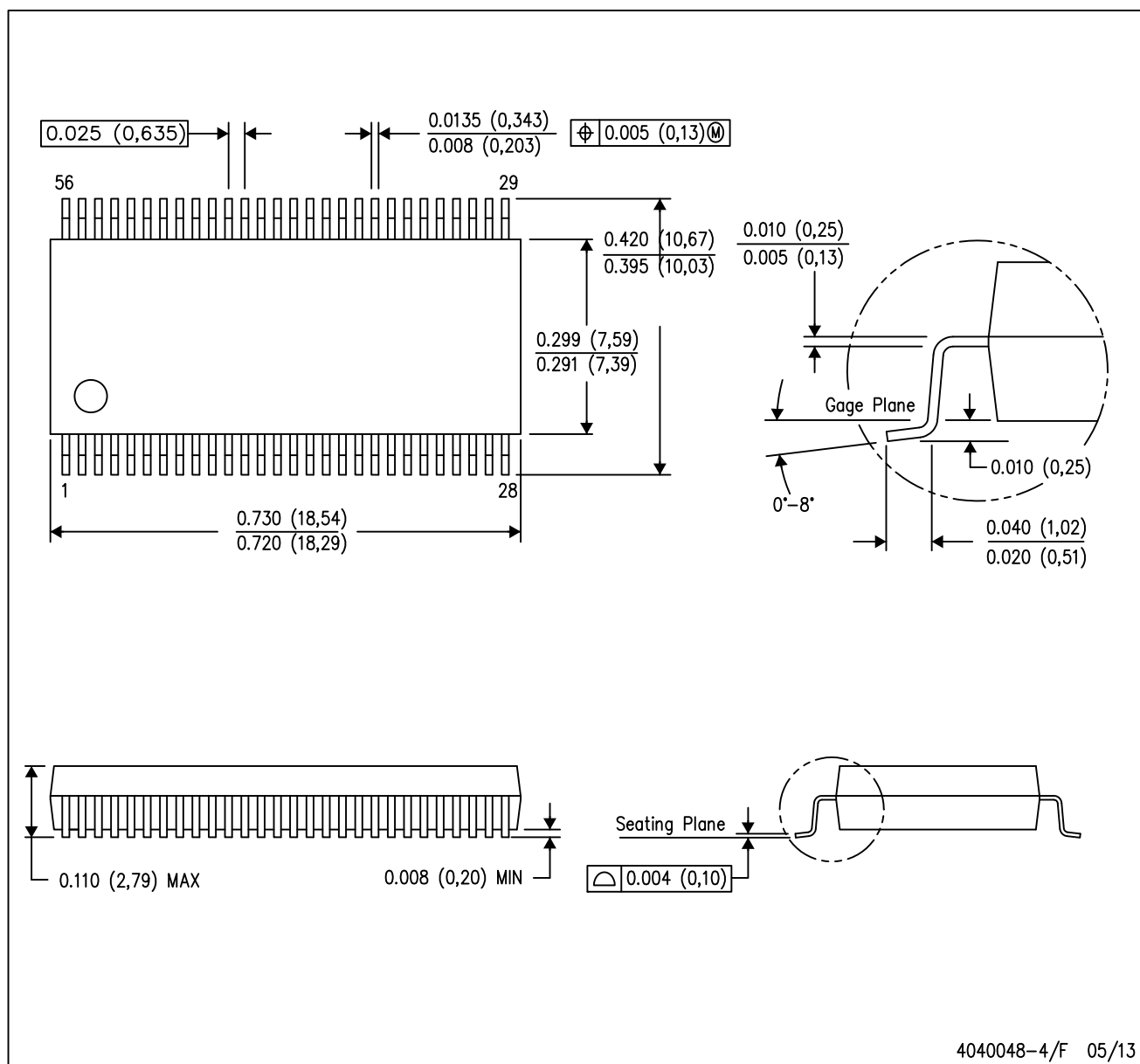


*All dimensions are nominal

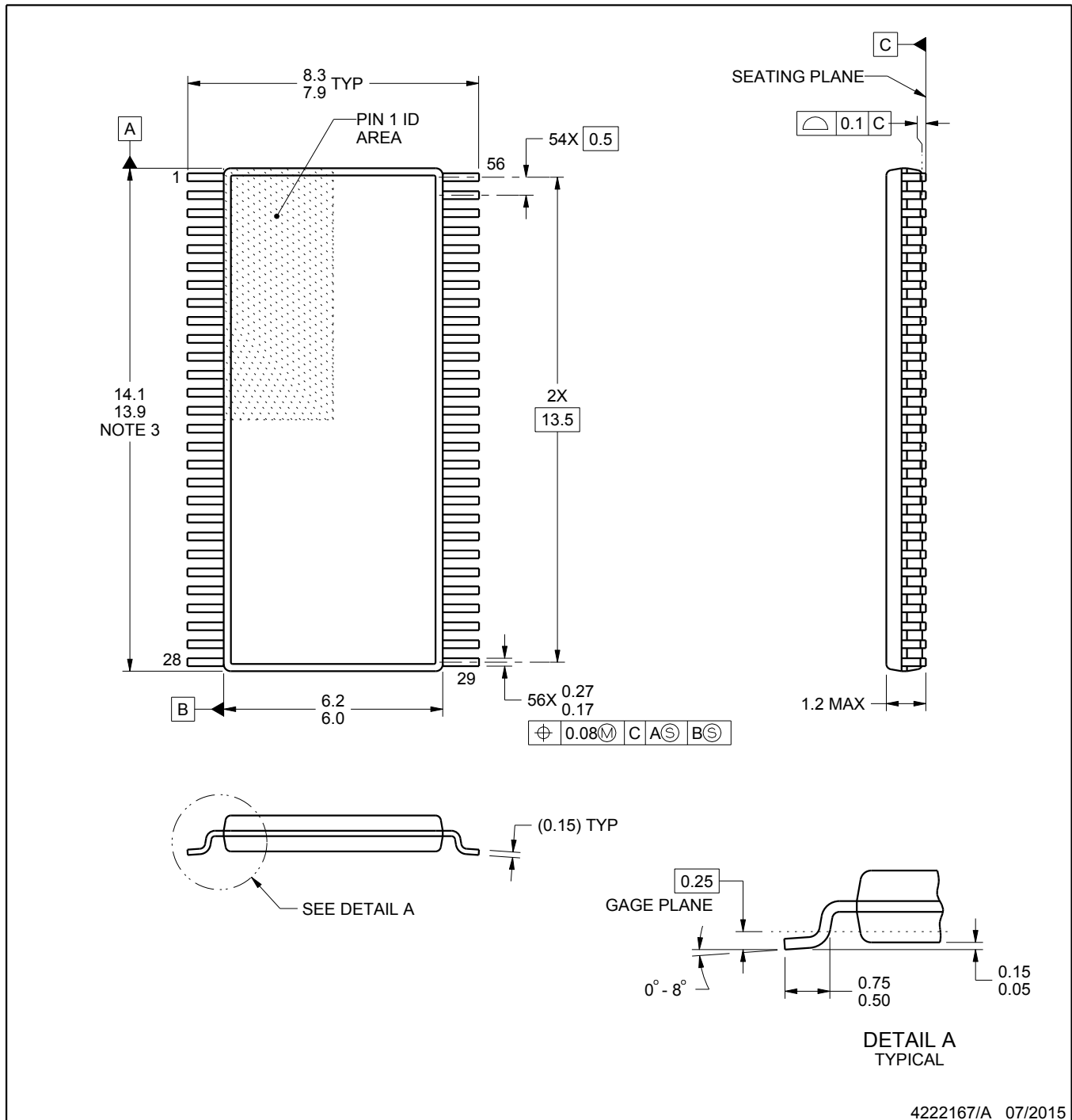
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABT16646DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ABT16646DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MO-118



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NOTES:

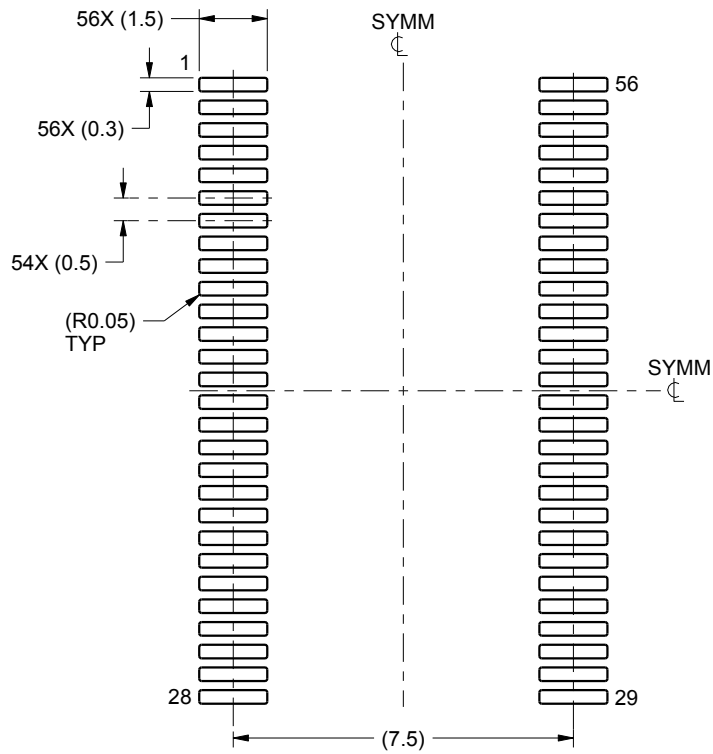
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

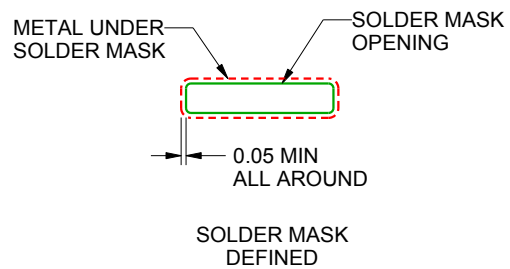
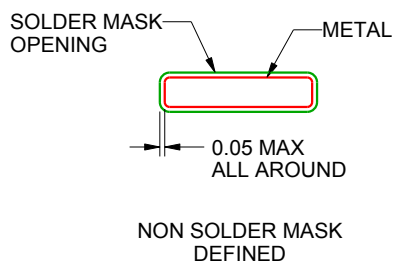
DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

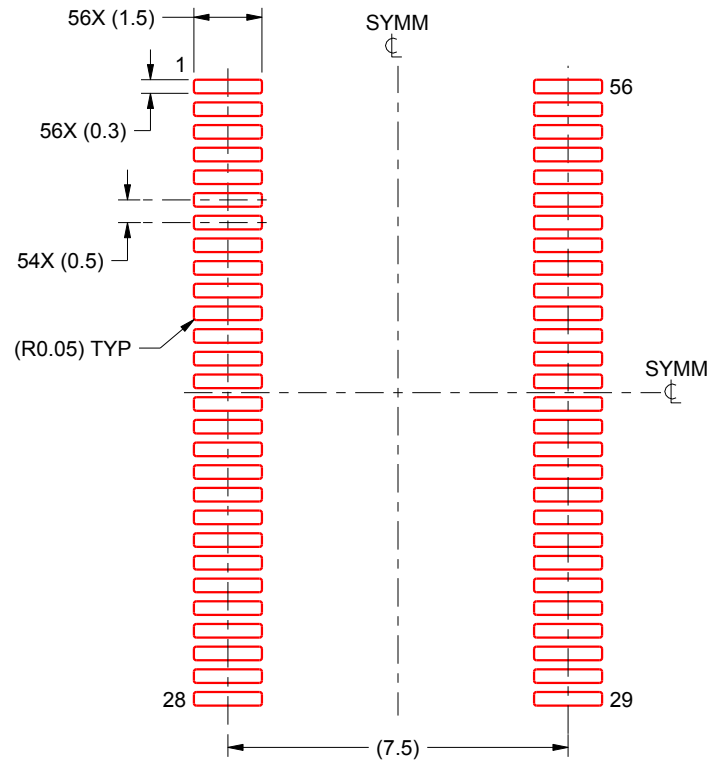
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DGG0056A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4222167/A 07/2015

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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